

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	N/A	Silicon Carbide (SiC)	409-21-2	0.05195	100.0	0.86
			Subtotal	0.05195	100	0.86
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01299	0.03	0.2151
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01299	0.03	0.2151
	Copper alloy	Iron (Fe)	7439-89-6	0.04331	0.1	0.717
	Copper alloy	Copper (Cu)	7440-50-8	43.24193	99.84	715.8528
			Subtotal	43.31122	100	717
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.19878	4.0	36.4
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	8.24544	15.0	136.5
	Filler	Silica fused	60676-86-0	40.67752	74.0	673.4
	Flame retardant	Metal hydroxide		3.84787	7.0	63.7
			Subtotal	54.96961	100	910
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.51015	100.0	25
			Subtotal	1.51015	100	25
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00278	2.0	0.046
	Lead alloy	Silver (Ag)	7440-22-4	0.00347	2.5	0.0575
	Lead alloy	Lead (Pb)	7439-92-1	0.13268	95.5	2.1965
			Subtotal	0.13893	100	2.3
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01812	100.0	0.3
			Subtotal	0.01812	100	0.3
			Total	99.99998	100	1655.46

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.